

**SCREEN Semiconductor Solutions Co., Ltd.**

## **SCREEN Signs Joint Development Agreement with IBM for Next Generation Cleaning Processes**

Kyoto, Japan – November 15, 2022 – SCREEN Semiconductor Solutions, Inc. and IBM have recently signed a joint development agreement aimed at developing cleaning processes for next-generation devices. Through this agreement, SCREEN will incorporate first-hand knowledge of cleaning process issues in advanced semiconductor manufacturing, and will quickly provide feedback to the development of its cleaning process technology and equipment.

In the semiconductor industry, the need for advanced cleaning processes is becoming even more critical as scaling, stacking, and chipletization of semiconductors continues to progress. At the same time, the introduction of EUV lithography has increased the number of cleaning processes due to demand for wafer backside and bevel cleaning to improve yields. In addition, from the view of sustainability, it is important to conserve energy during equipment operation, reduce chemical consumption and waste, and improve semiconductor manufacturing yields.

Against the backdrop of these industry trends, we have entered into a joint development agreement with IBM to accelerate the development of cleaning processes and mass production equipment that anticipate market needs several years into the future.

By working with IBM, we will promote the advanced development of cleaning technology and continue to provide solutions that contribute to the evolution of technological development in the semiconductor industry and maximize added value for device manufacturers.

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